



Connectors > PCB Connectors > Card Edge Connectors > PCI & PCI Express Connectors



Connector System: **Board-to-Board**

Number of Positions: **64**

PCI Generation: **4**

Centerline (Pitch): **1 mm [.039 in]**

Contact Mating Area Plating Material Thickness: **[15 µin]**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| Connector & Contact Terminates To | Printed Circuit Board |
| Connector System | Board-to-Board |
| Sealable | No |

Configuration Features

| | |
|--|----------|
| Number of PCB Mount Retention Features | 2 |
| Number of Positions | 64 |
| PCB Mount Orientation | Vertical |
| Ejector | Without |

Body Features

| | |
|-----------------------|-------|
| Primary Product Color | Black |
|-----------------------|-------|

Contact Features

| | |
|---|------------------|
| PCB Contact Termination Area Plating Material Thickness | 2.54 µm[100 µin] |
| Contact Mating Area Plating Material | Gold |
| PCB Contact Termination Area Plating Material Finish | Matte |
| Contact Underplating Material | Nickel |



| | |
|---|--------------|
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Copper Alloy |
| Contact Current Rating (Max) | 1.1 A |
| | 15 µin |

Termination Features

| | |
|---|---------------|
| Termination Method to Printed Circuit Board | Surface Mount |
|---|---------------|

Mechanical Attachment

| | |
|--------------------------|---------------|
| PCB Mount Retention Type | SMT Hold-Down |
| Connector Mounting Type | Board Mount |

Housing Features

| | |
|--------------------|------------------|
| Housing Material | LCP With 30% G.F |
| Centerline (Pitch) | 1 mm[.039 in] |

Dimensions

| | |
|--------------------------|-------------------|
| Connector Length | 39 mm[1.535 in] |
| PCB Thickness (Accepted) | 1.57 mm |
| Connector Height | 11.25 mm[.442 in] |
| Connector Width | 8.75 mm[.345 in] |

Usage Conditions

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|-----------------------------|---------------------------|
| Operating Temperature Range | -40 - 85 °C[-40 - 185 °F] |
|-----------------------------|---------------------------|

Operation/Application

| | |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Industry Standards

| | |
|----------------|-------------|
| Bus Type | PCI Express |
| PCI Generation | 4 |

Packaging Features

| | |
|------------------|------------|
| Packaging Method | Box & Tray |
|------------------|------------|

Product Compliance

For compliance documentation, visit the product page on [TE.com](#)>

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |



| | |
|--|---|
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JAN 2024 (240) Candidate List Declared Against: JAN 2024 (240) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Not reviewed for solder process capability |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

TE Part # 5-2337939-4
PCIE GEN4 CON,SMT,164POS,30u",MYLAR,HT

TE Part # 1734774-1
PCI EXP 3.1L 36 POS WHT G/F

Customers Also Bought

TE Part # T1319320120-000
H32A-TS-M20

TE Part # 218083-000
55A0811-12-6

TE Part # 755167-000
TXR61AC00-1406AI

TE Part # 3-2176067-2
CRG0201 1% 44R2

Documents

- CAD Files
- 3D PDF



3D

Customer View Model

[ENG_CVM_CVM_6-2337939-2_A.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_6-2337939-2_A.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_6-2337939-2_A.3d_stp.zip](#)

English

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Product Specifications

[Product Specification](#)

English

Agency Approvals

[UL Report](#)

English